

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 05-055401

(43)Date of publication of application : 05.03.1993

(51)Int.Cl.

H01L 23/12
// H05K 1/02

(21)Application number : 03-074134

(71)Applicant : IBIDEN CO LTD

(22)Date of filing : 13.03.1991

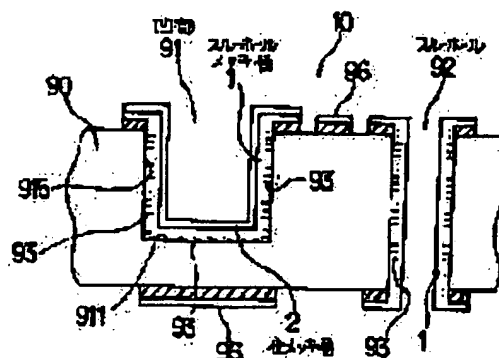
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(54) PRINTED WIRING BOARD

(57)Abstract:

PURPOSE: To provide a printed wiring board which has excellent humidity-proof characteristic and heat radiating characteristic and also facilitates wire bonding process and die bonding process.

CONSTITUTION: In a printed wiring board having a recess 91 for mounting electronic components and a through hole 92 on an organic resin substrate 90, the recess 91 and through hole 92 have a through hole plating layer 1 and the recess 91 has vertical wall surface formed by the counterboring process. Moreover, the outer most surface of the recess 91 is covered with gold plating layer 2.



LEGAL STATUS

[Date of request for examination] 13.03.1991

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 1853428

[Date of registration] 07.07.1994

[Number of appeal against examiner's
decision of rejection]

[Date of requesting appeal against examiner's
decision of rejection]

[Date of extinction of right] 12.10.2002

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